


APPLICATION DATA SHEET

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Title of Invention	[MOLD AND METHOD OF MOLDING SEMICONDUCTOR DEVICES]		
Application Type : regular, utility Attorney Docket Number : 11184-US-PA			
Correspondence address: Customer Number: 31561 			
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.